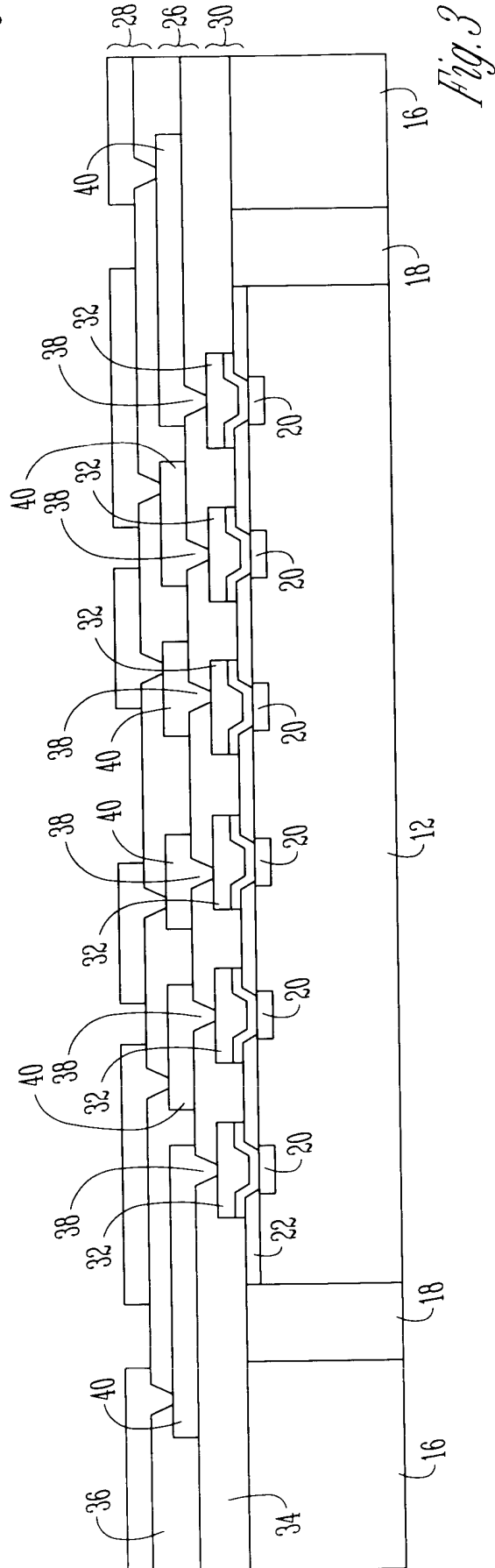
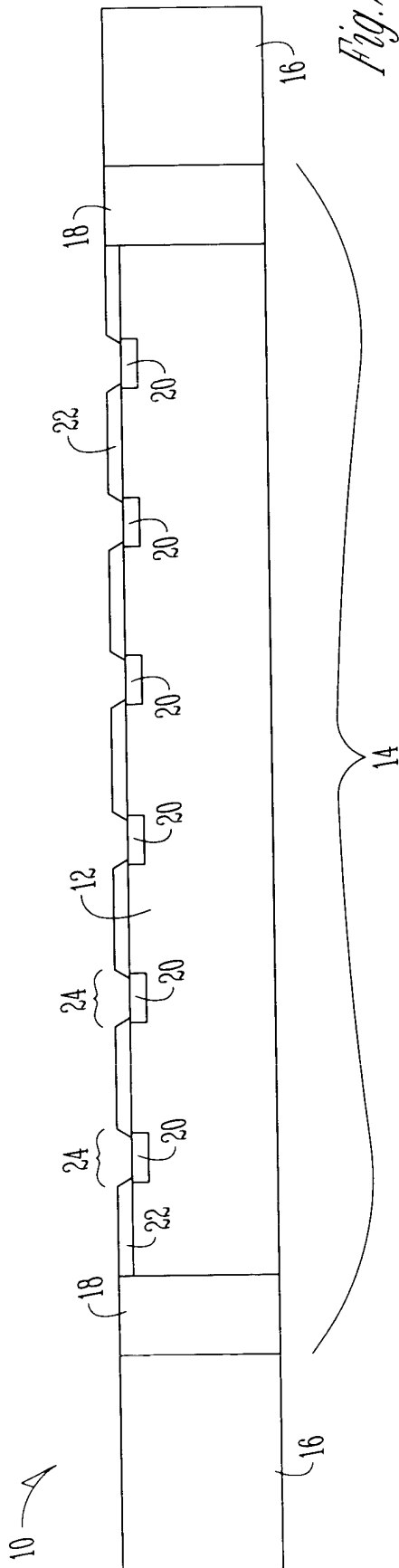


Fig. 1



TITLE: POLY[REDACTED] ENCAPSULATION MATERIAL WITH FIBROUS FILM[REDACTED] FOR USE IN
MICROELECTRONIC CIRCUIT PACKAGING
INVENTORS NAME: Steven Towle
DOCKET NO.: 884.415US1

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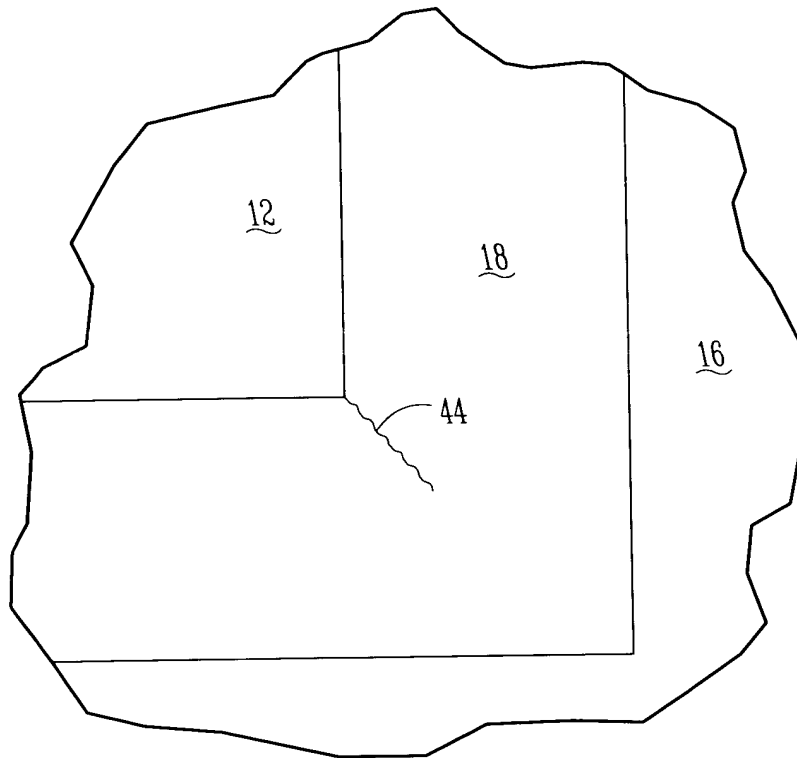


Fig. 4

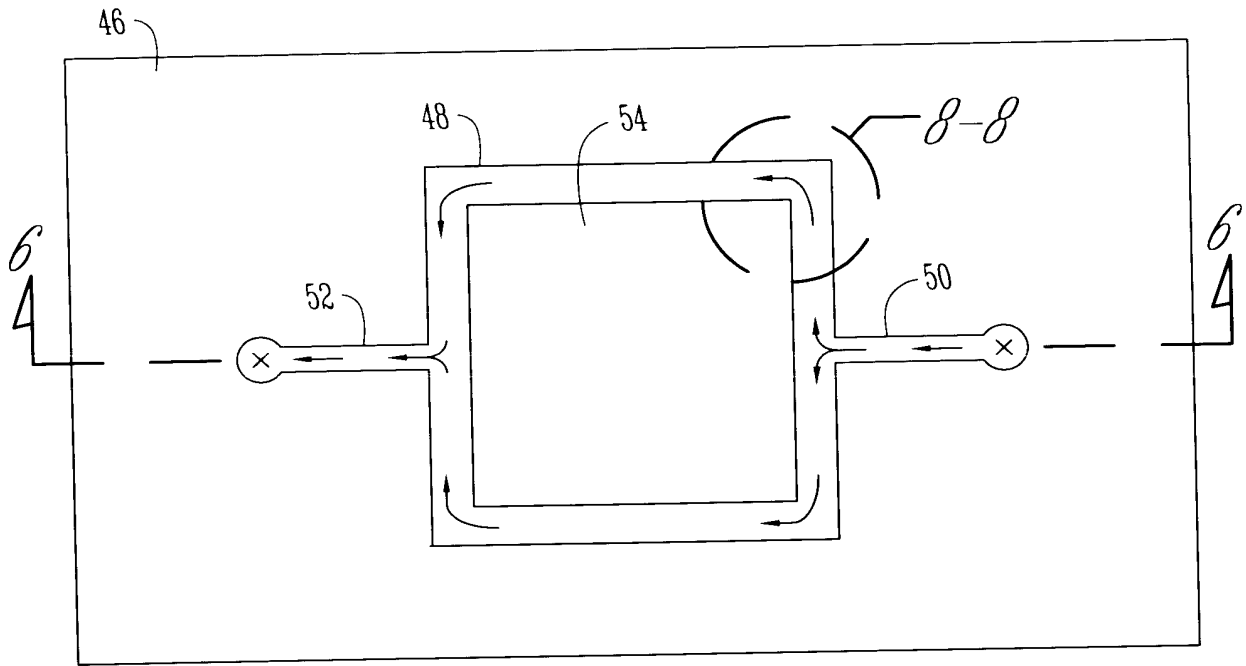


Fig. 5

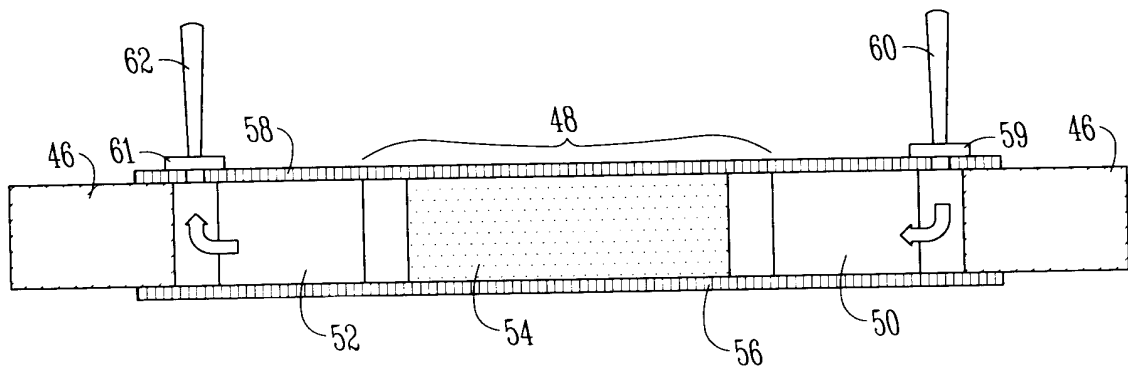


Fig. 6

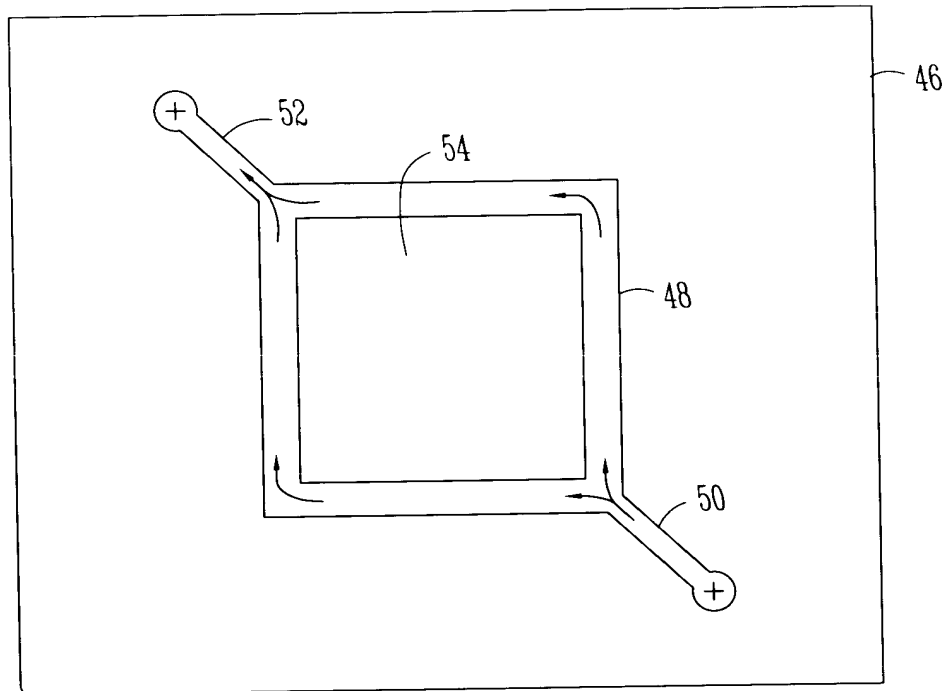


Fig. 7

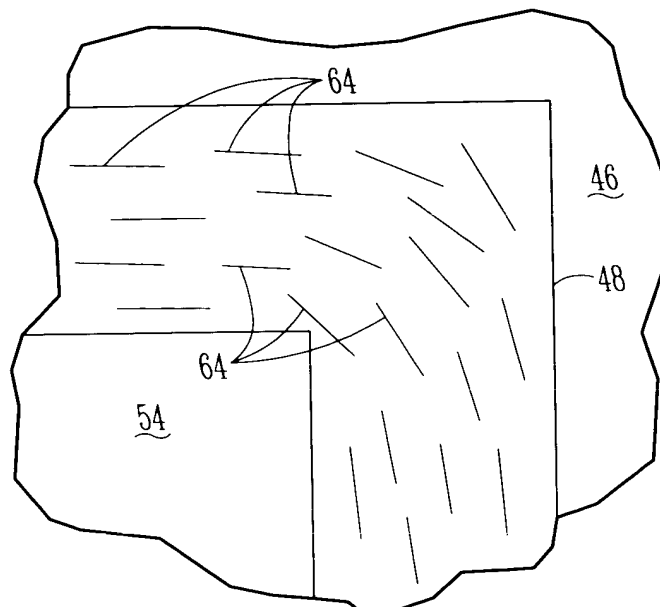


Fig. 8

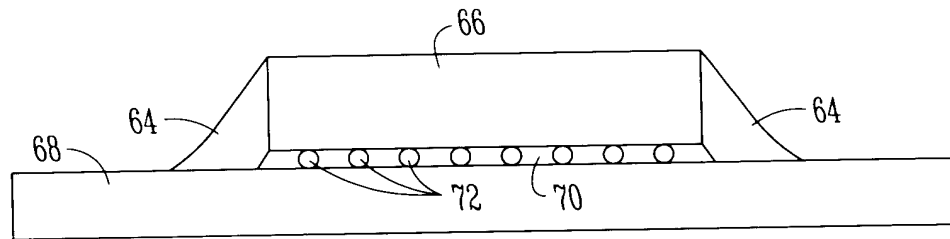


Fig. 9

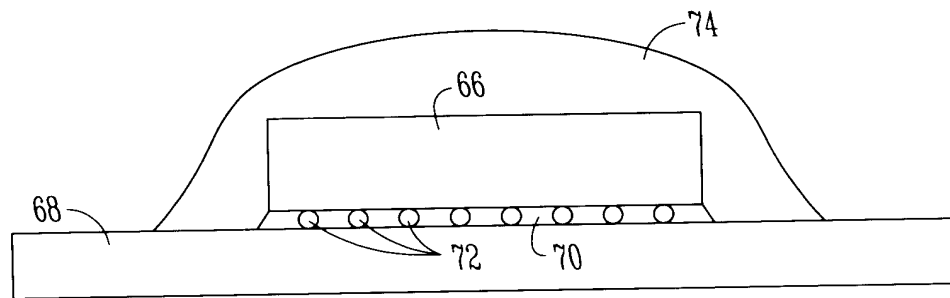


Fig. 10

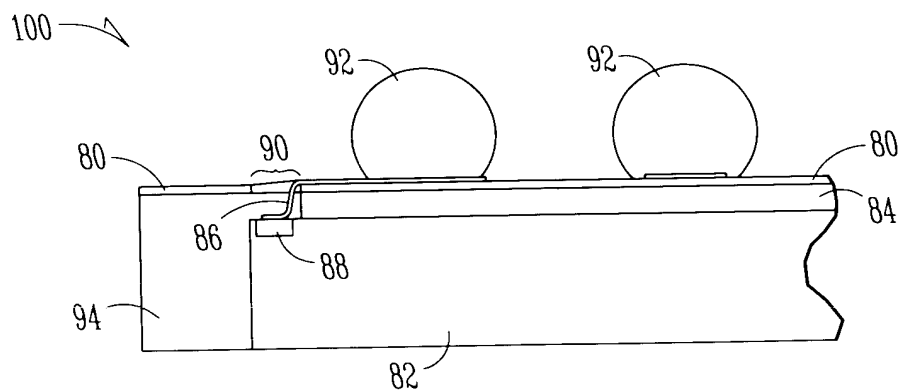


Fig. 11